

FIG.1A

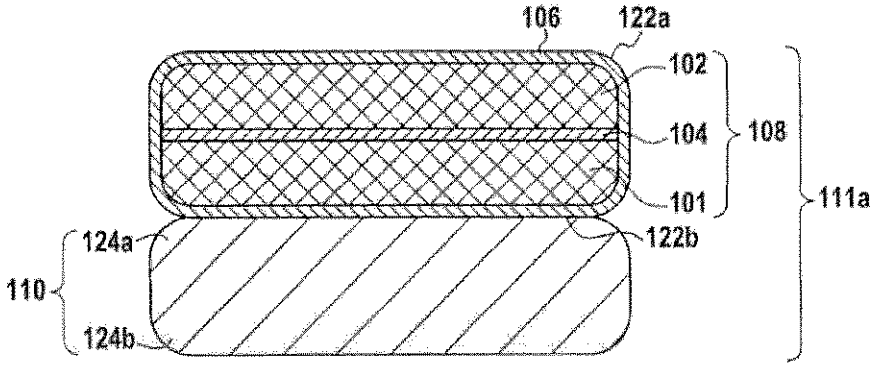


FIG.1B

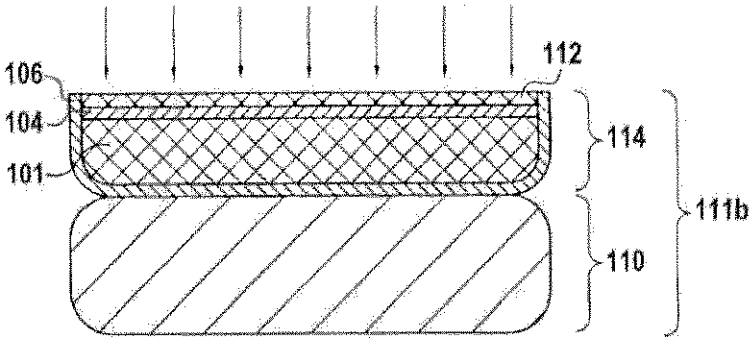


FIG.1C

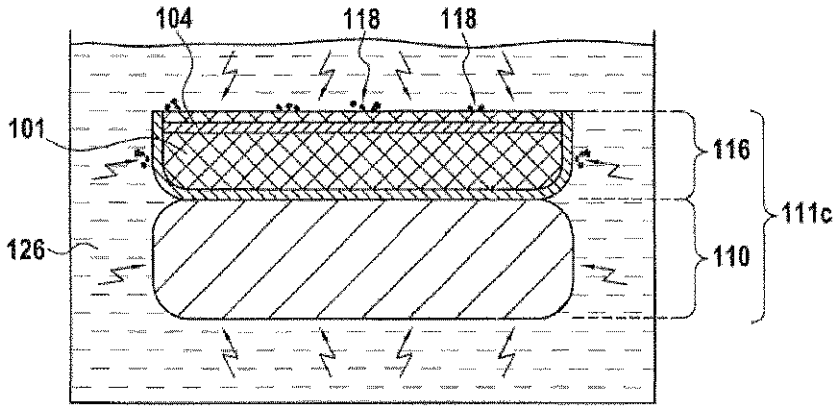


FIG.1D

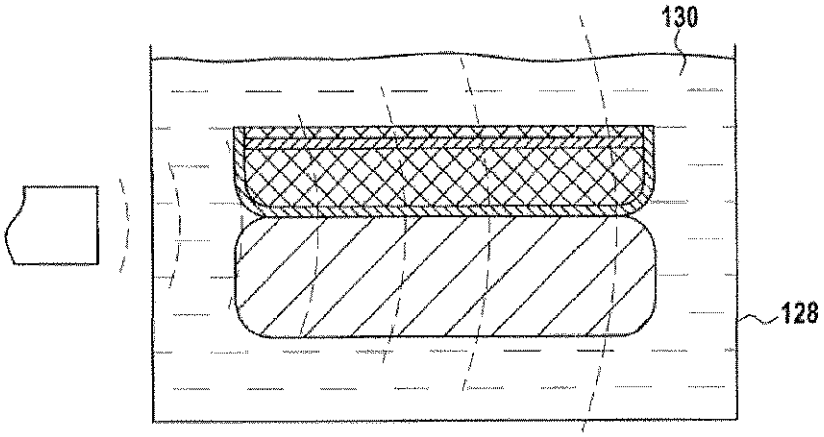


FIG.3

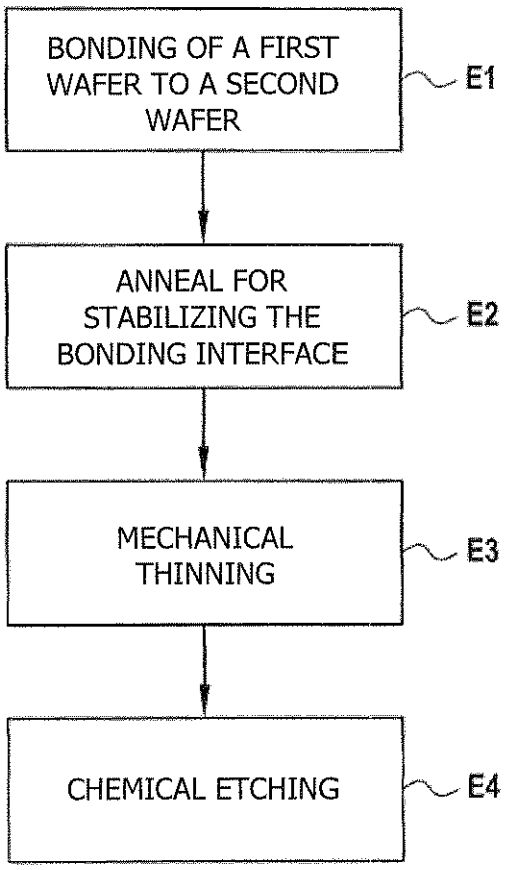

BONDING OF A FIRST WAFER TO A SECOND WAFER
E1
ANNEAL FOR STABILIZING THE BONDING INTERFACE
E2
MECHANICAL THINNING
E3
CHEMICAL ETCHING
E4

FIG.2